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(12) **United States Design Patent**
Cola et al.

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(54) **FLEXIBLE HEAT SINK**

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(73) Assignee: **CARBICE CORPORATION**, Atlanta, GA (US)

(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **15 Years**

(21) Appl. No.: **29/703,632**

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(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179
CPC . H05K 7/20254; H05K 7/20418; F28F 3/022; F28F 3/04; F28F 21/065; H01L 23/367; H01L 23/3672; H01L 23/3677; H01L 23/36; G02B 1/111; A61B 17/50; A61M 37/0015
See application file for complete search history.

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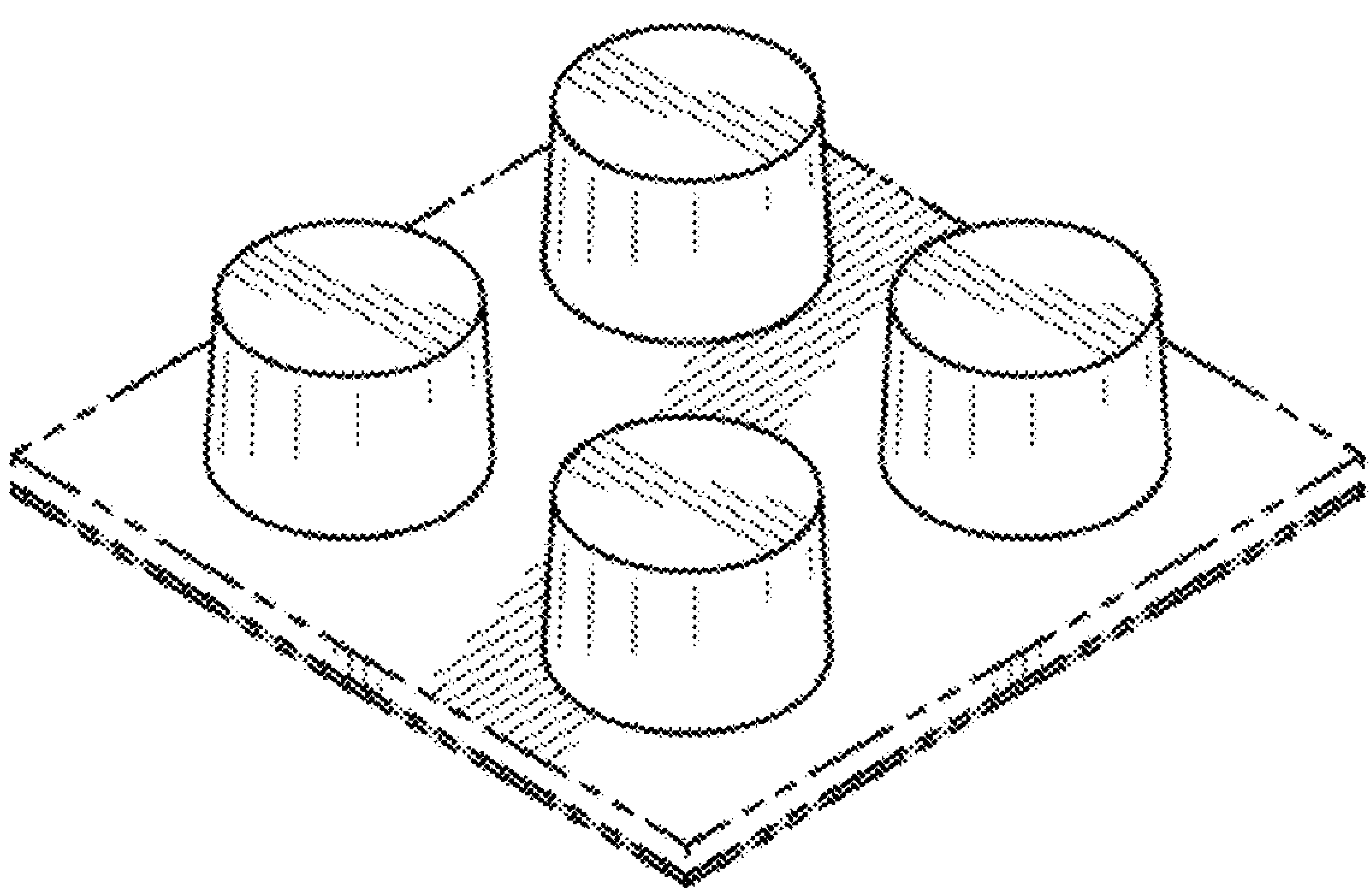

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Primary Examiner — April Rivas
(74) *Attorney, Agent, or Firm* — Pabst Patent Group LLP

(57) **CLAIM**

We claim the ornamental design for a flexible heat sink, as follows.

DESCRIPTION

The patent or application file contains at least one drawing executed in color. Copies of this patent or patent application publication with color drawing(s) will be provided by the Office upon request and payment of the necessary fee.

FIG. **1** is a top isometric view of a flexible heat sink showing our new design in grey scale;
FIG. **2** is a front elevation view thereof, each of the right elevation, left elevation, and rear elevation views being a mirror image thereof;
FIG. **3** is a top view thereof;
FIG. **4** is a bottom view thereof;
FIG. **5** is a top isometric view of the heat sink illustrated in FIGS. **1** to **4** on a curved surface;
FIG. **6** is a front elevation view thereof, the rear elevation view being a mirror image thereof;
FIG. **7** is a top view thereof;
FIG. **8** is a bottom view thereof; and
FIG. **9** is a top isometric view of a heat sink showing our new design in color;
FIG. **10** is a front elevation view thereof, each of the right elevation, left elevation, and rear elevation views being a mirror image thereof;
FIG. **11** is a top view thereof;
FIG. **12** is a bottom view thereof;
FIG. **13** is a top isometric view of the heat sink illustrated in FIGS. **10** to **13** on a curved surface;
FIG. **14** is a front elevation view thereof, the rear elevation view being a mirror image thereof;
FIG. **15** is a top view thereof;
FIG. **16** is a bottom view thereof; and
FIG. **17** is a top isometric view of a heat sink showing our new design in color;
FIG. **18** is a front elevation view thereof, each of the right elevation, left elevation, and rear elevation views being a mirror image thereof;
FIG. **19** is a top view thereof;
FIG. **20** is a bottom view thereof;
FIG. **21** is a top isometric view of the heat sink illustrated in FIGS. **17** to **20** on a curved surface;
FIG. **22** is a front elevation view thereof, the rear elevation view being a mirror image thereof;
FIG. **23** is a top view thereof; and,
FIG. **24** is a bottom view thereof.

The shade lines in the Figures show contour and not surface ornamentation.
The white and black broken dash-dot-dot lines in the views define boundary lines and are not part of the claimed design.
The evenly broken lines are used to depict environmental features for illustrative purposes only and form no part of the claimed design.

1 Claim, 6 Drawing Sheets
(2 of 6 Drawing Sheet(s) Filed in Color)

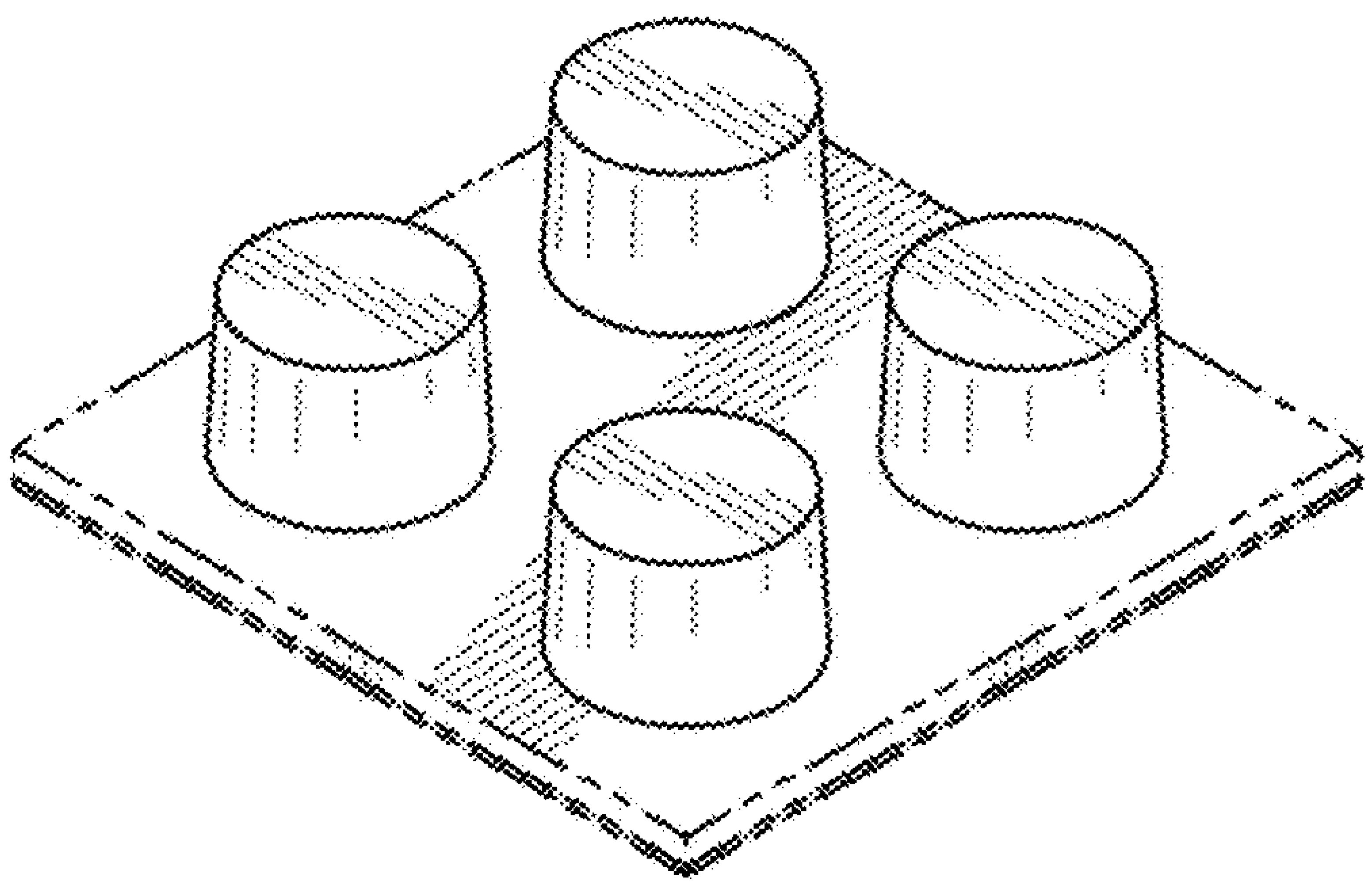


FIG. 1

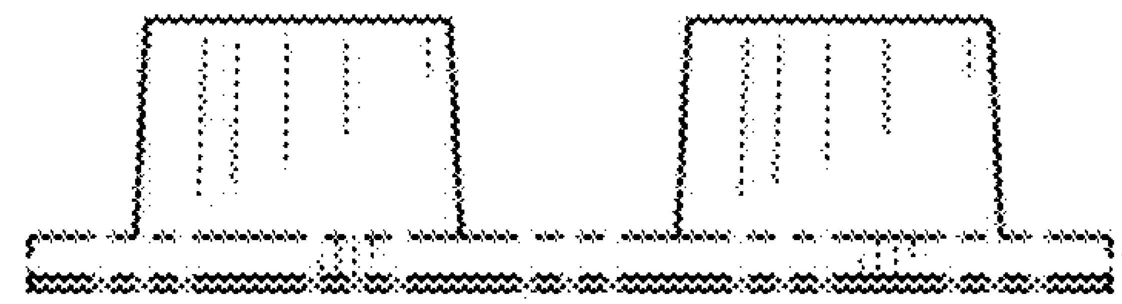


FIG. 2

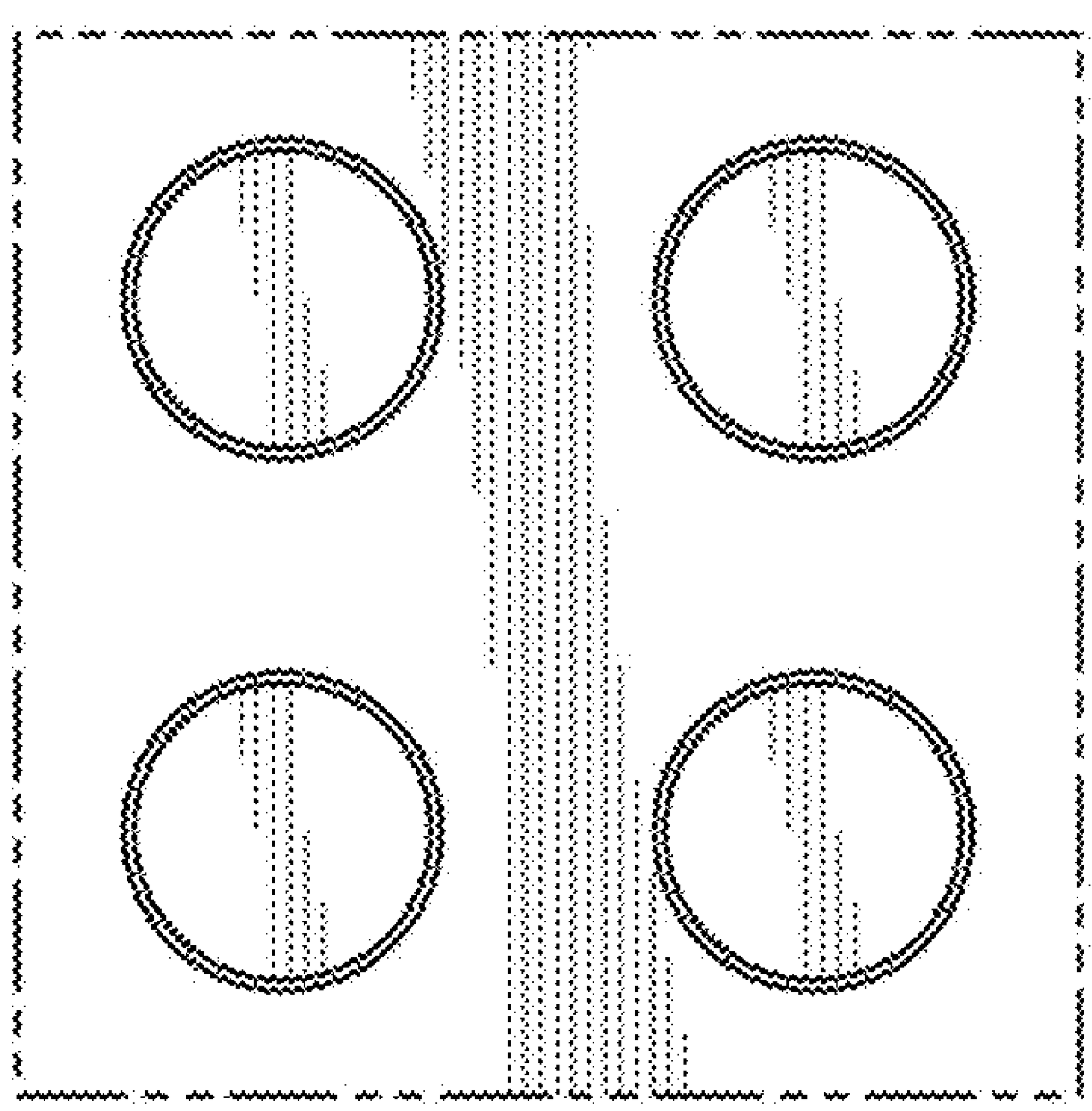


FIG. 3

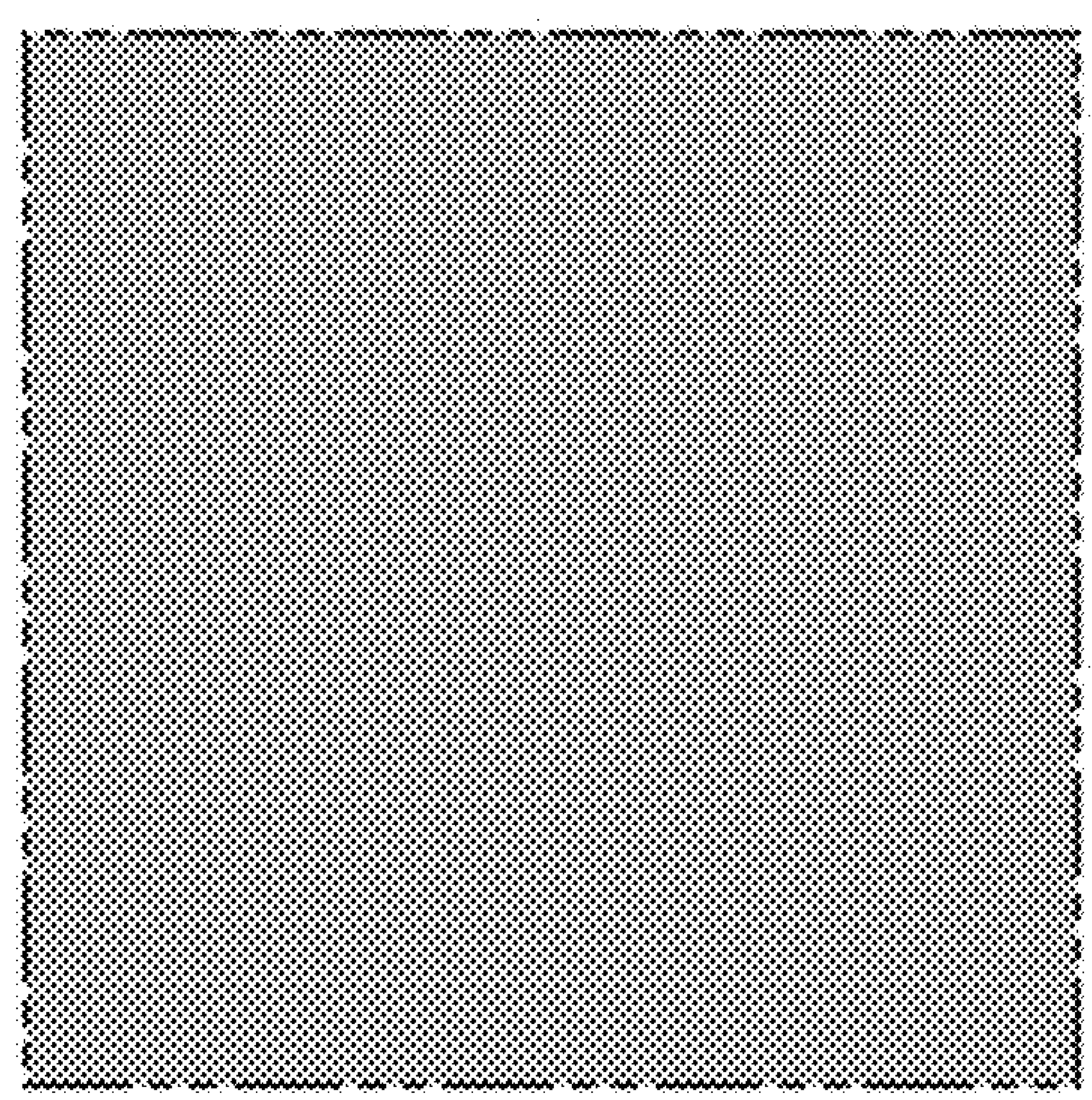


FIG. 4

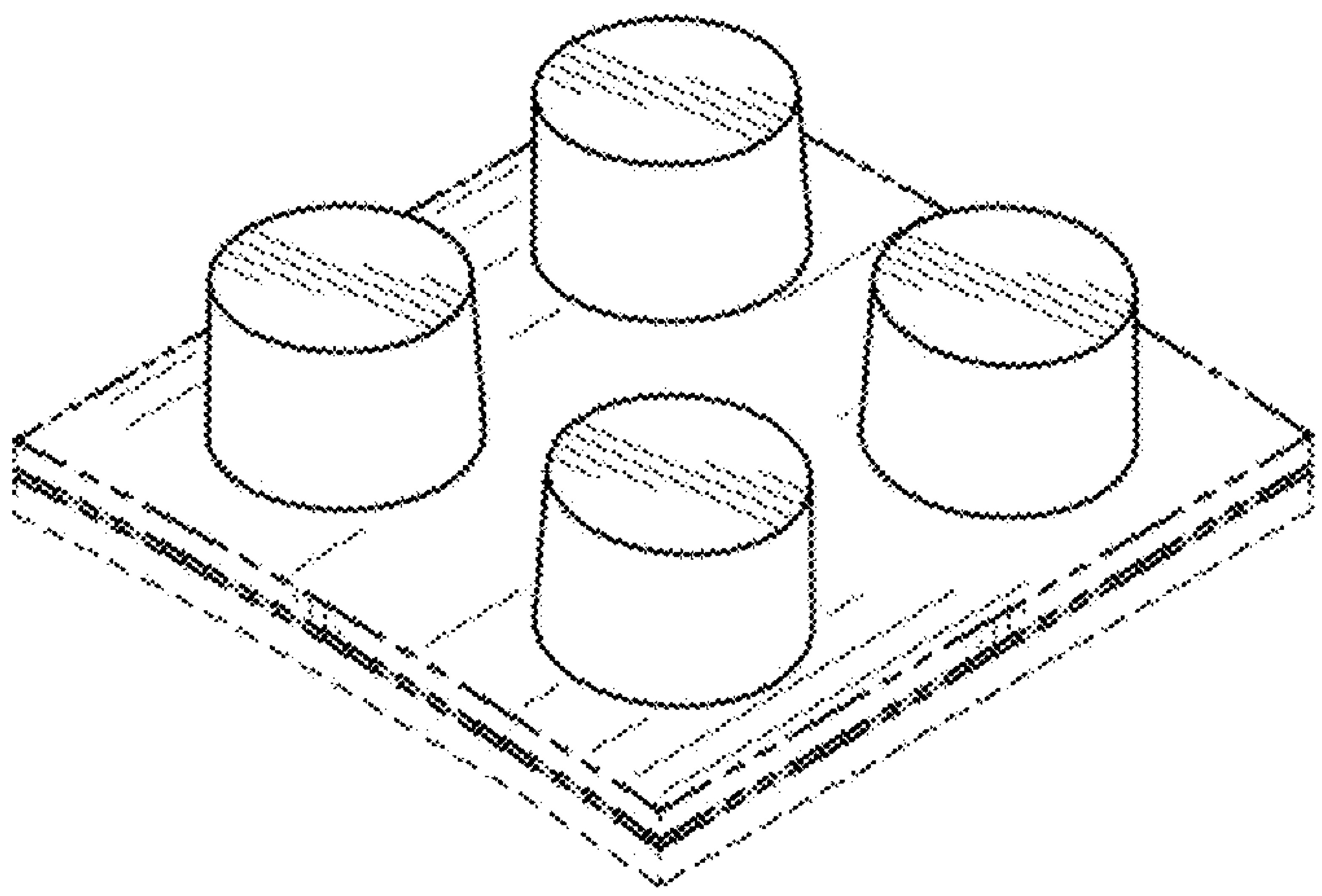
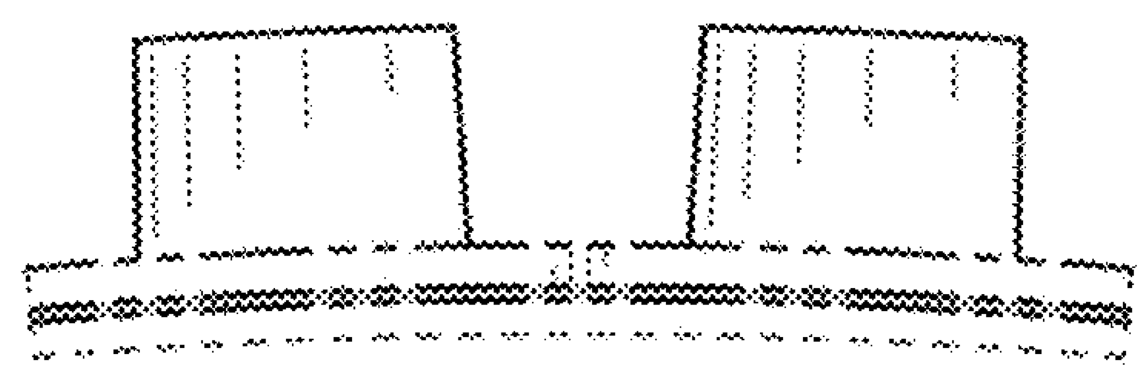


FIG. 5



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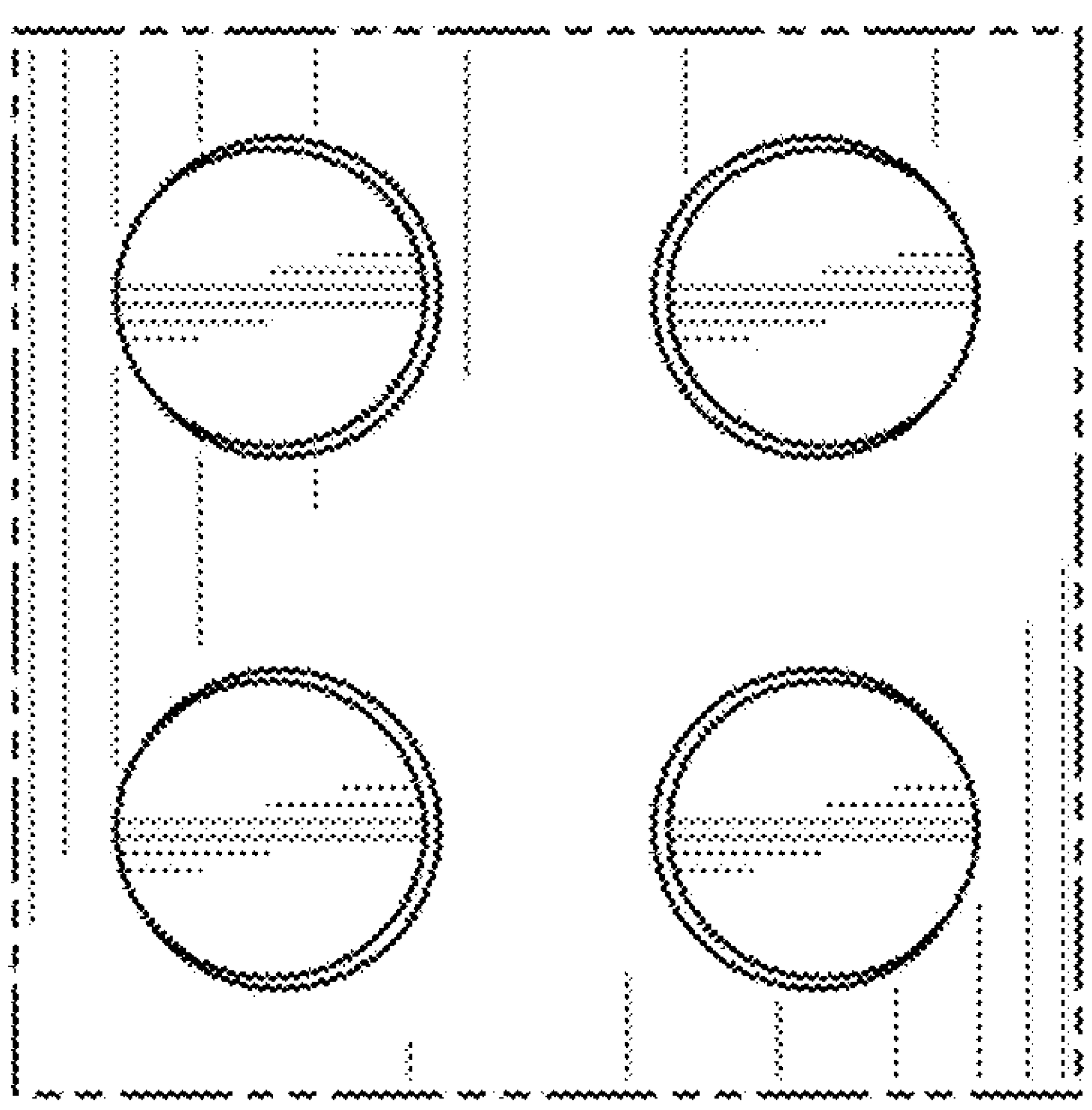

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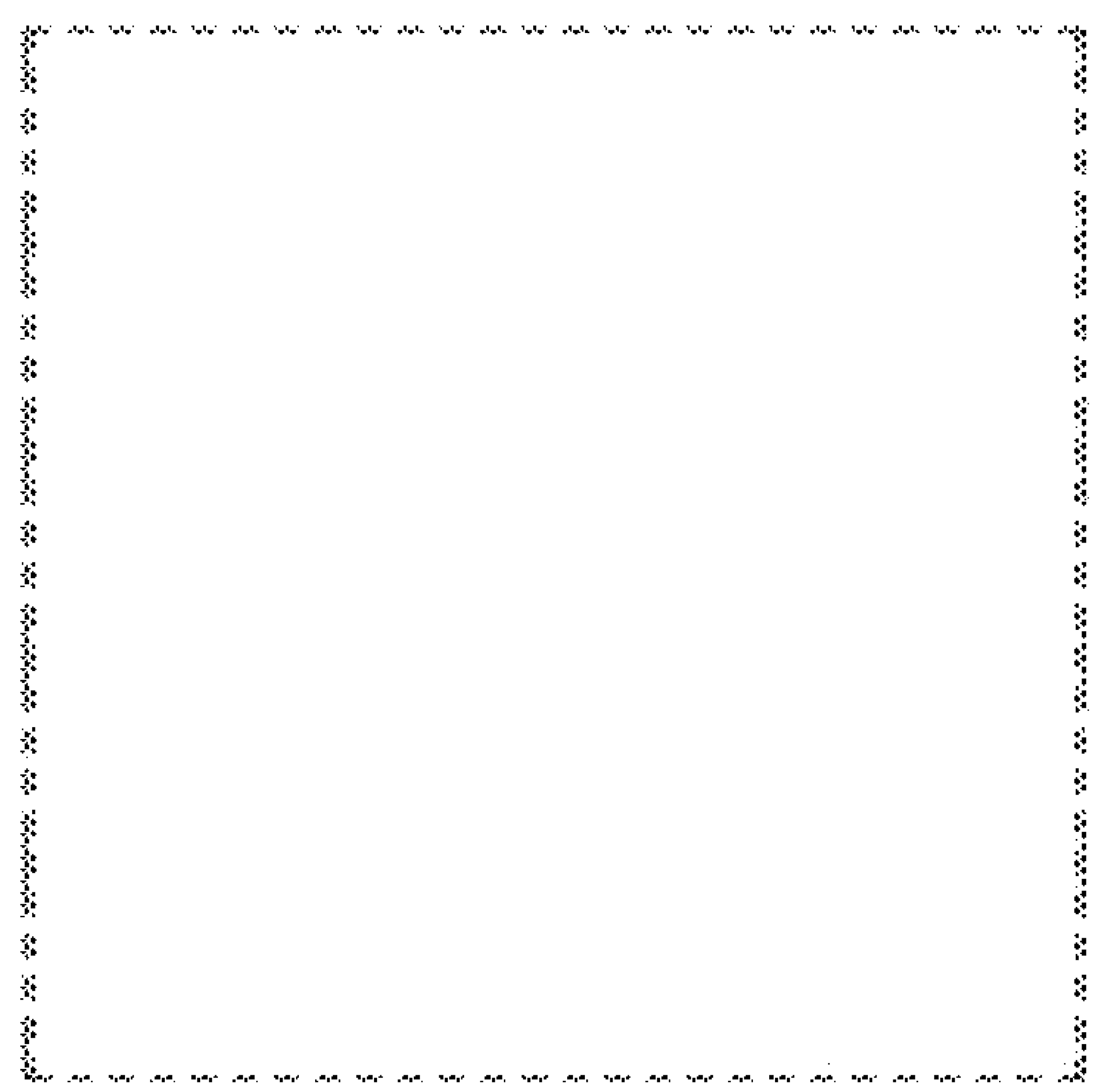


FIG. 8

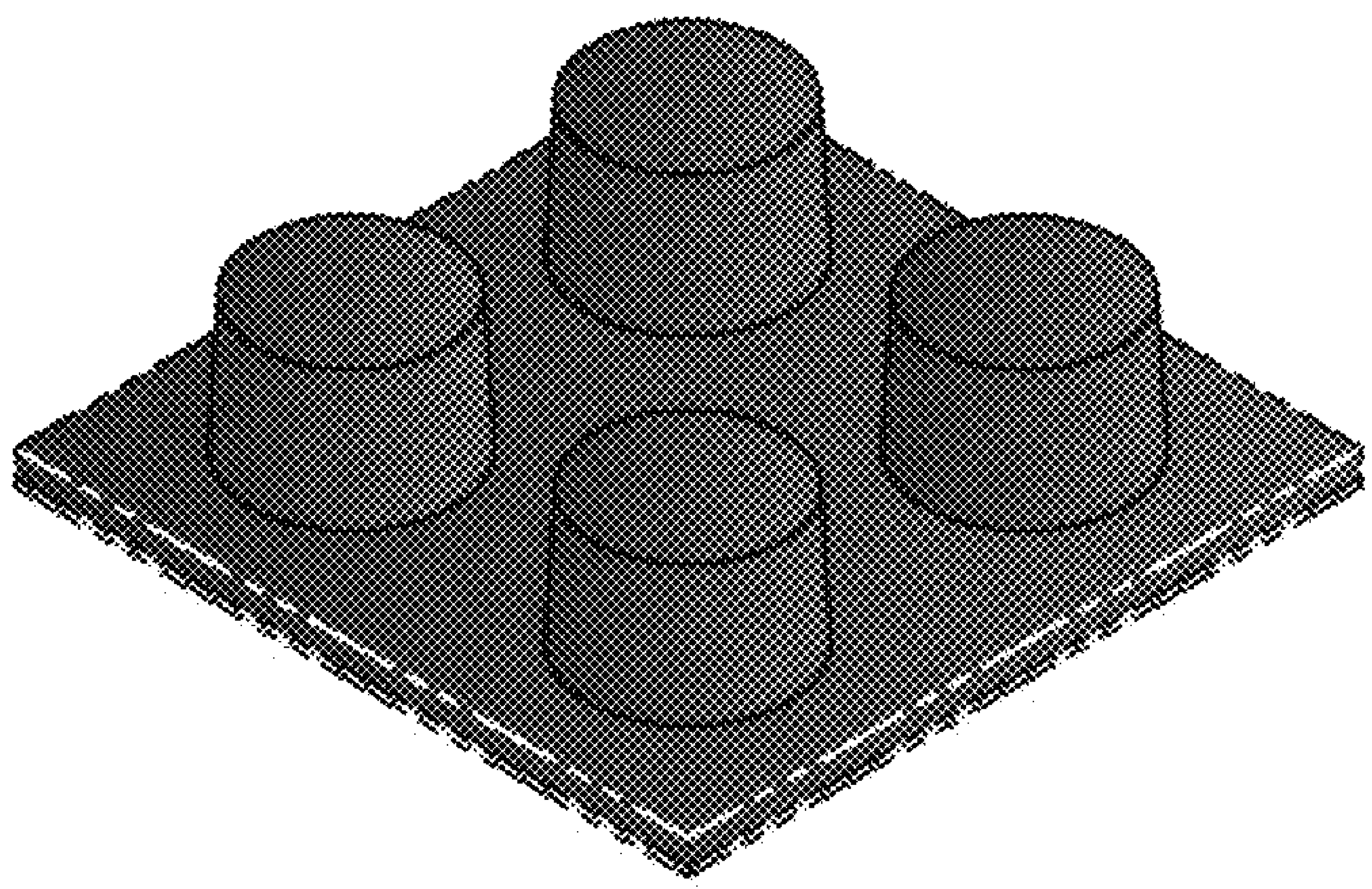


FIG. 9

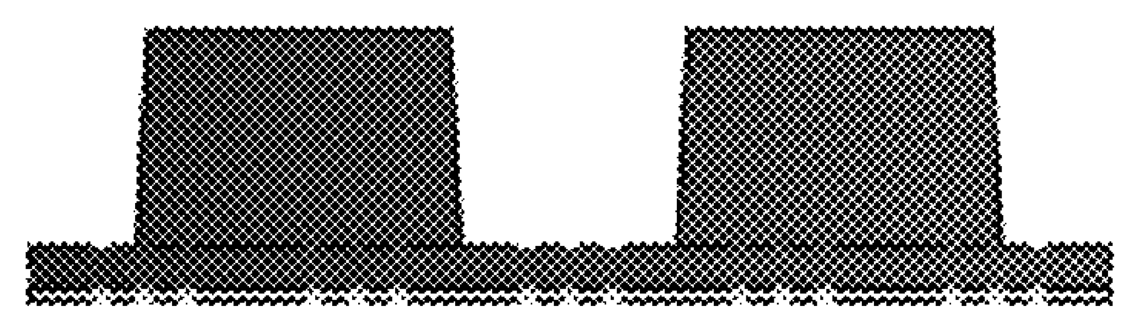


FIG. 10

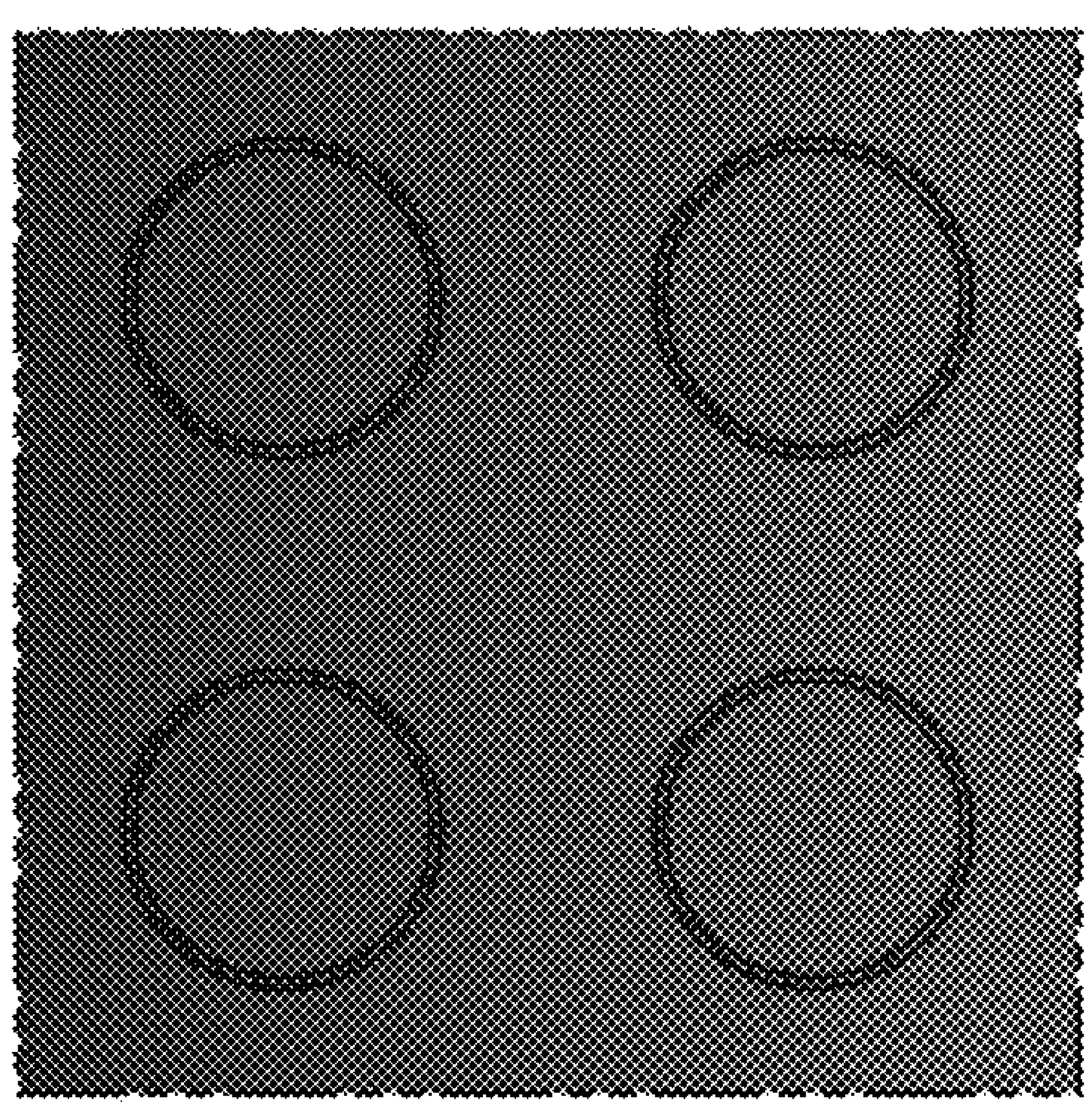


FIG. 11

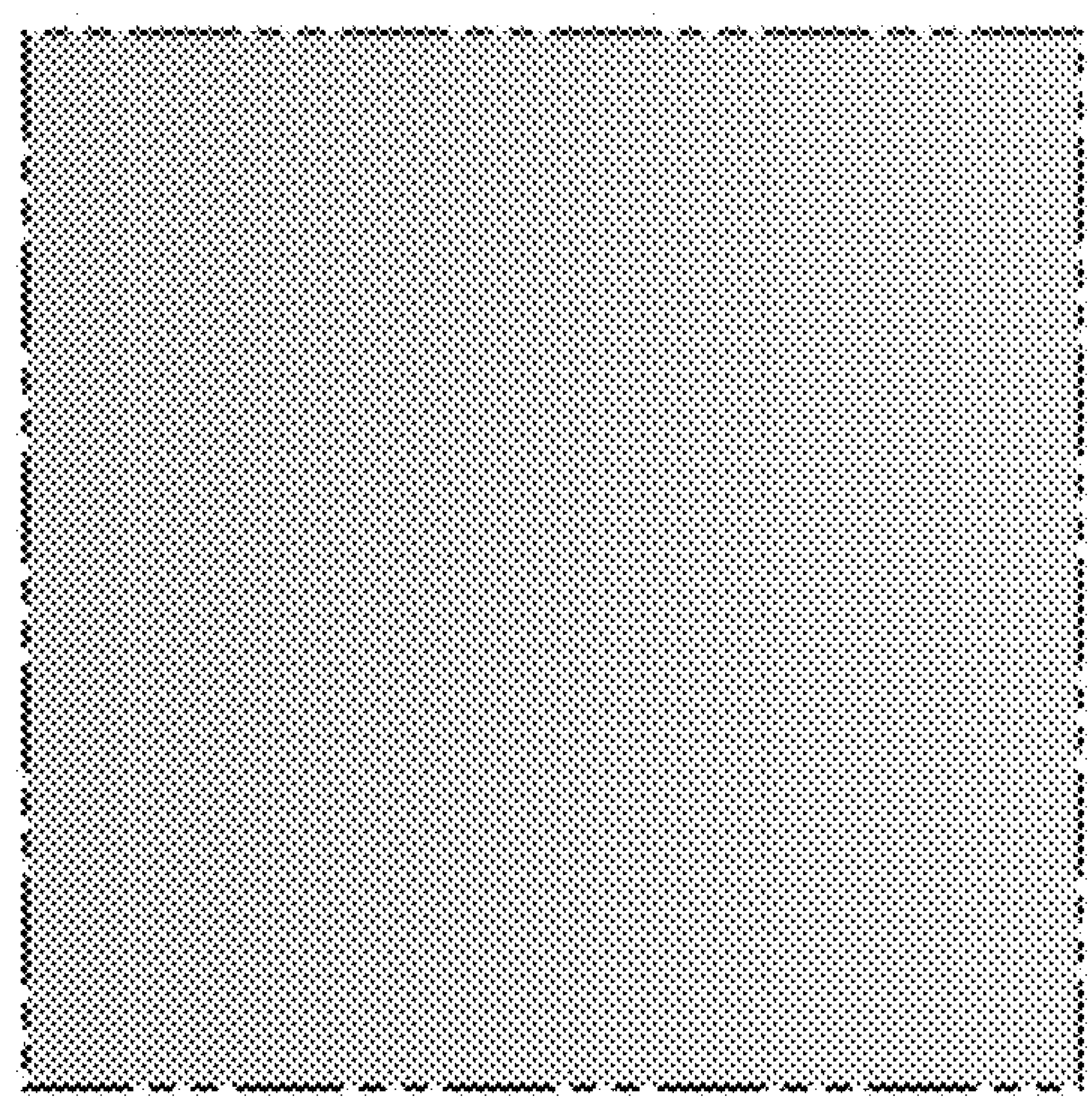


FIG. 12

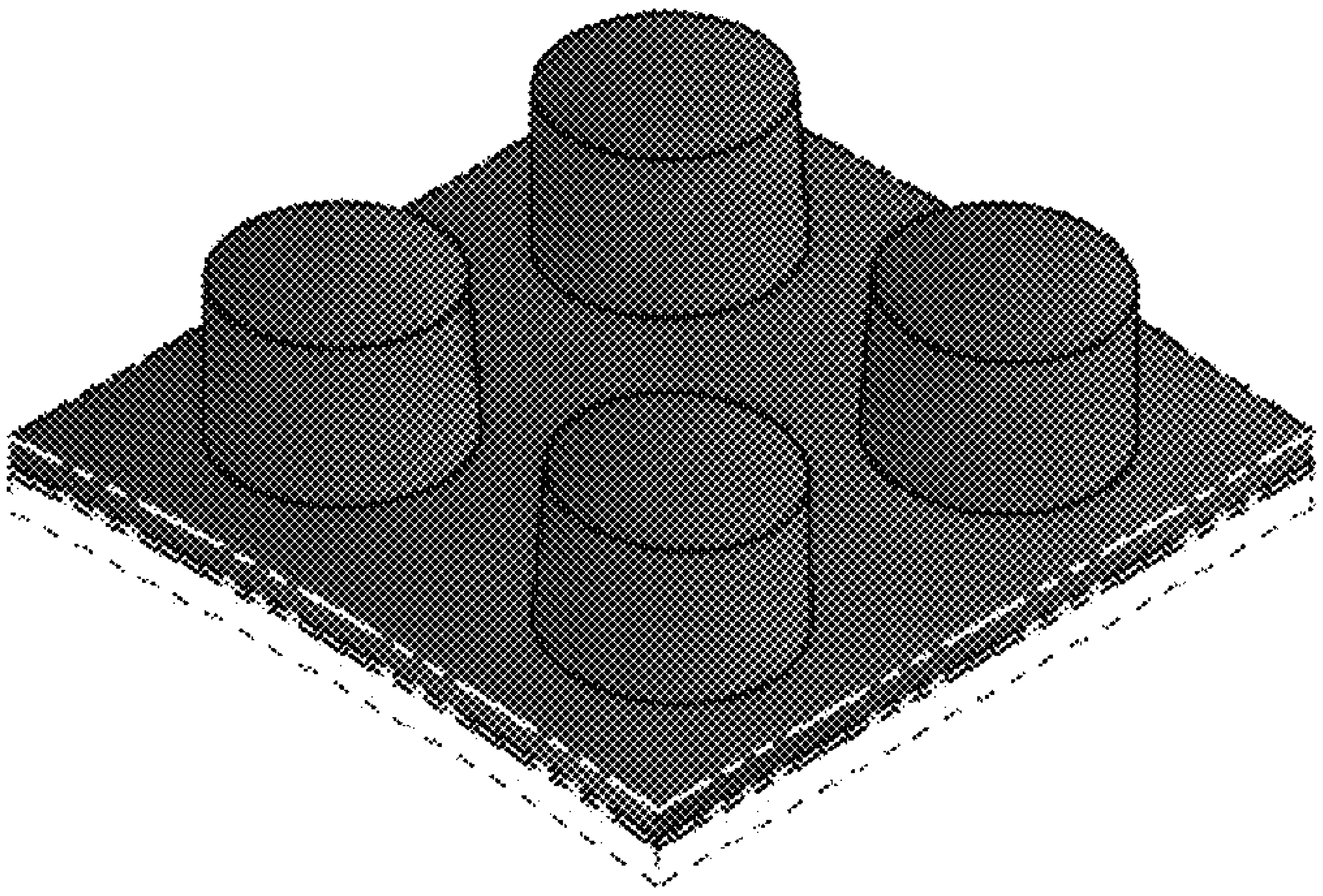


FIG. 13

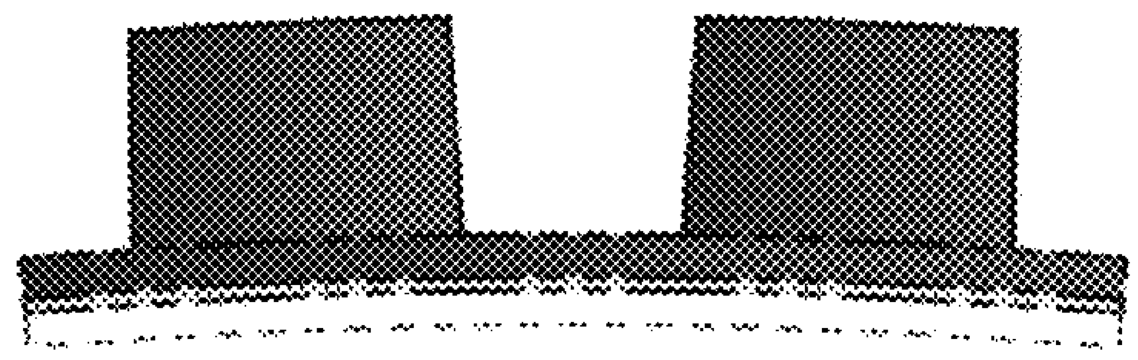


FIG. 14

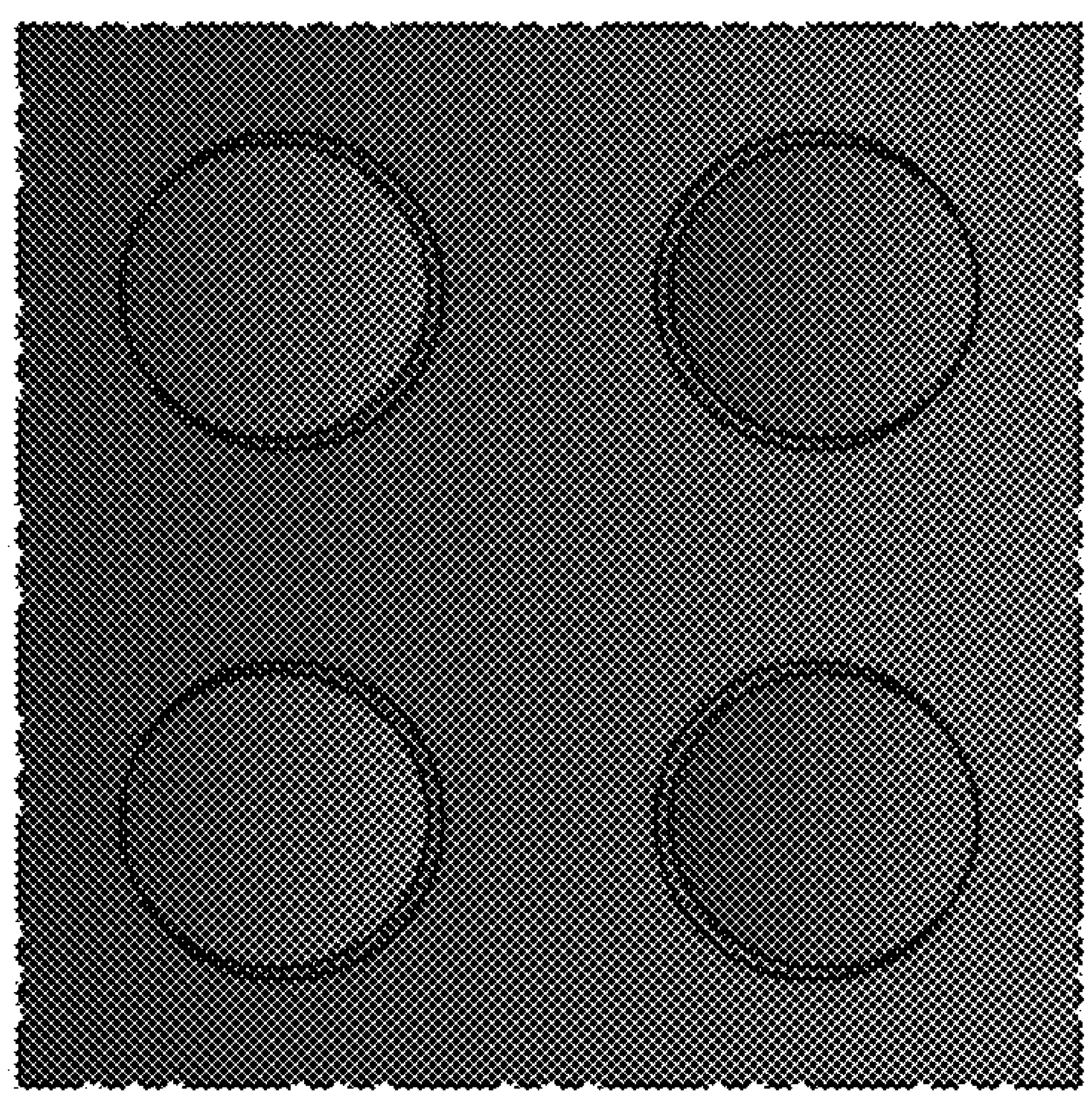


FIG. 15

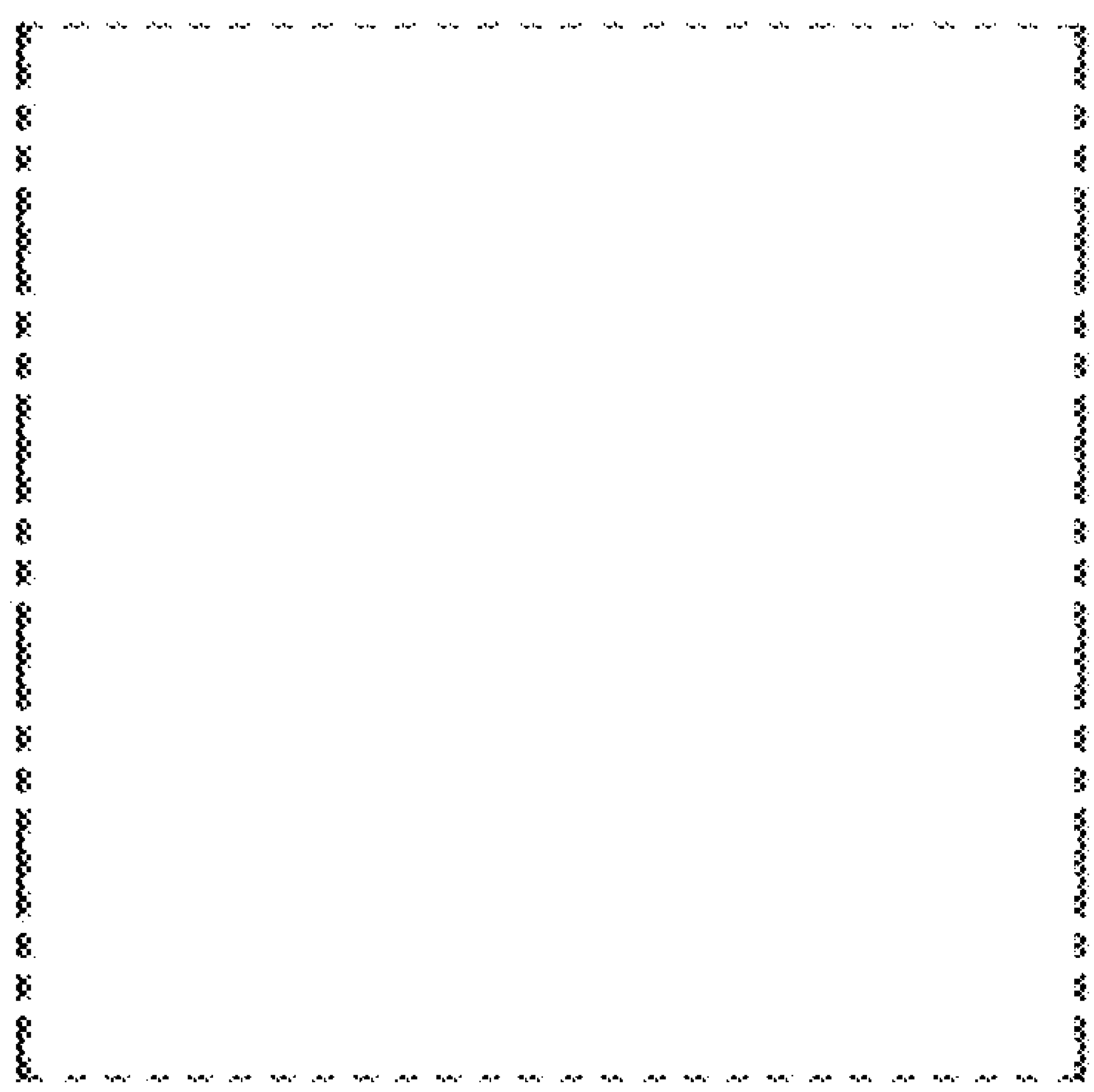
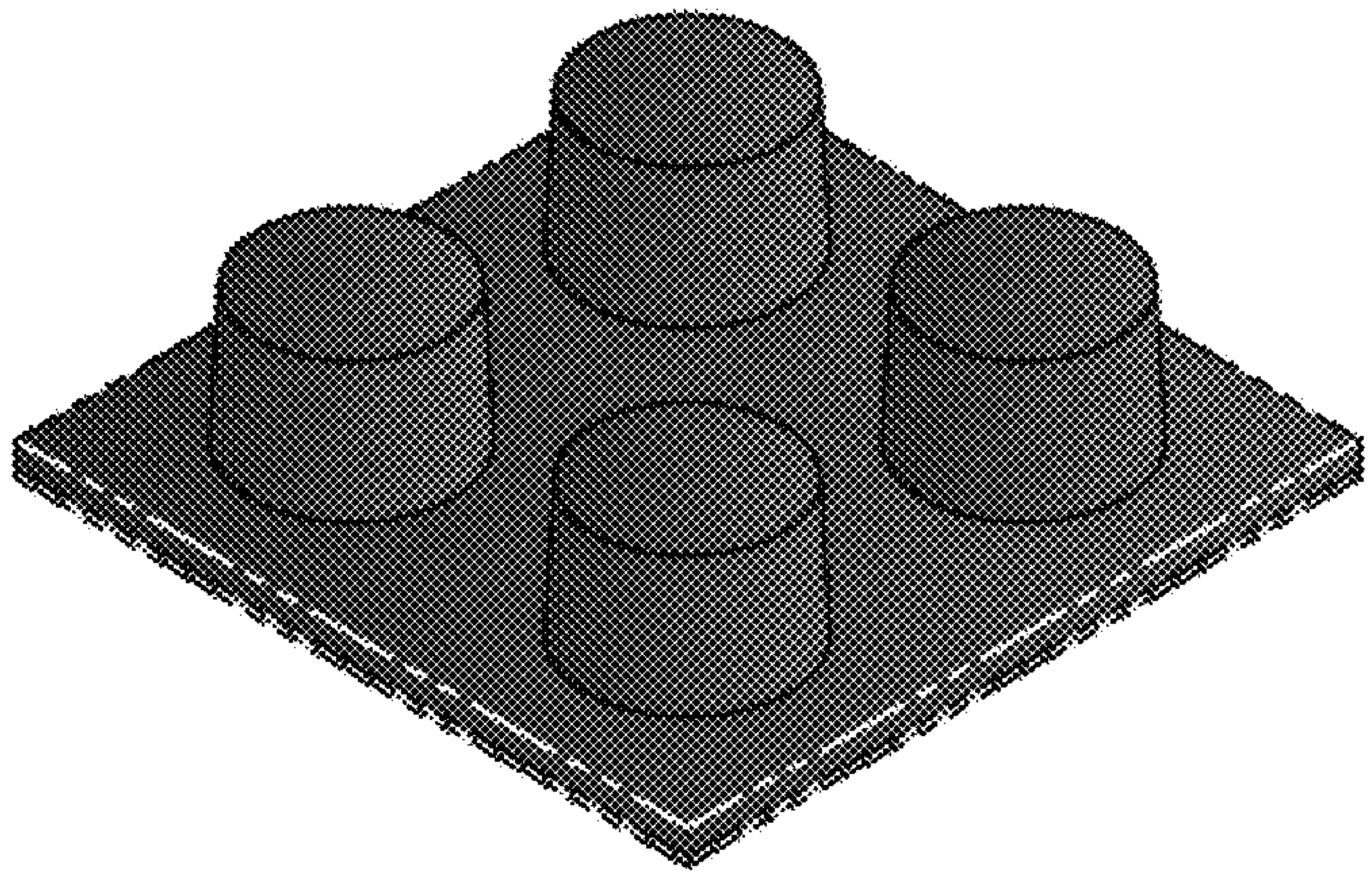


FIG. 16



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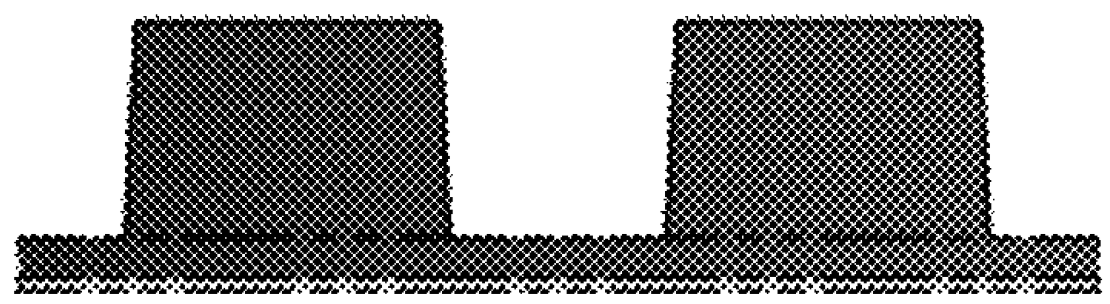

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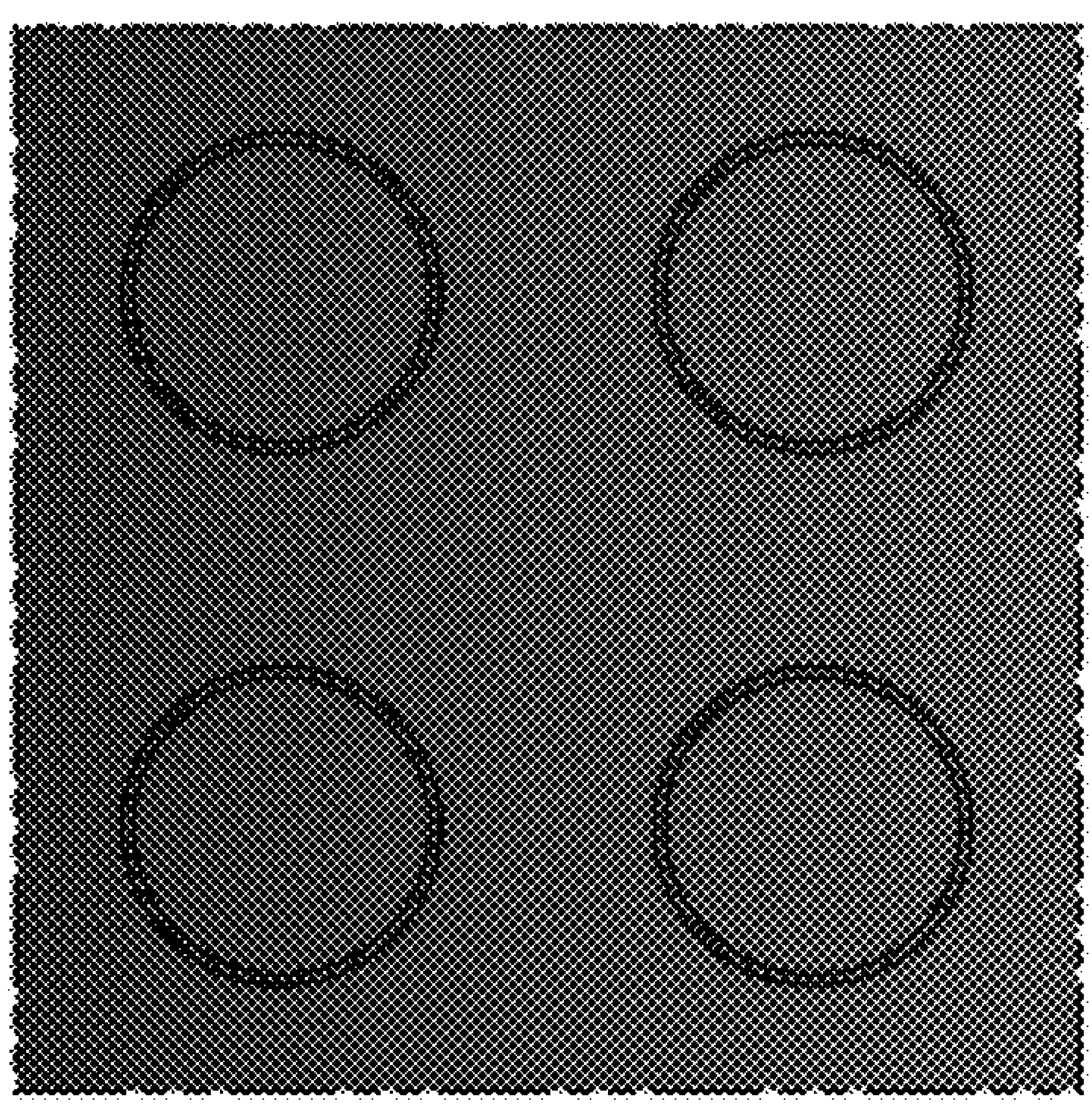

FIG. 19

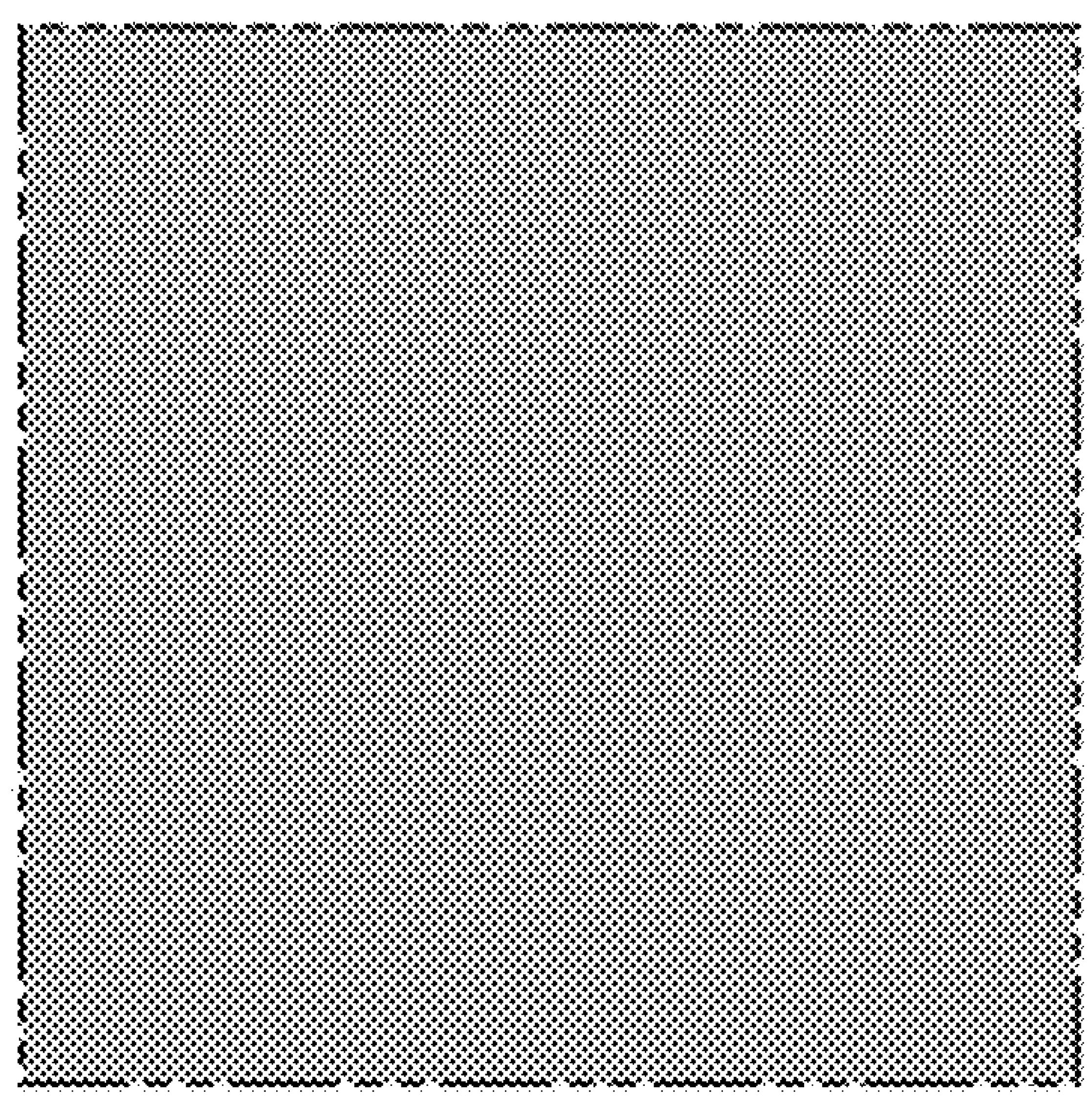

FIG. 20

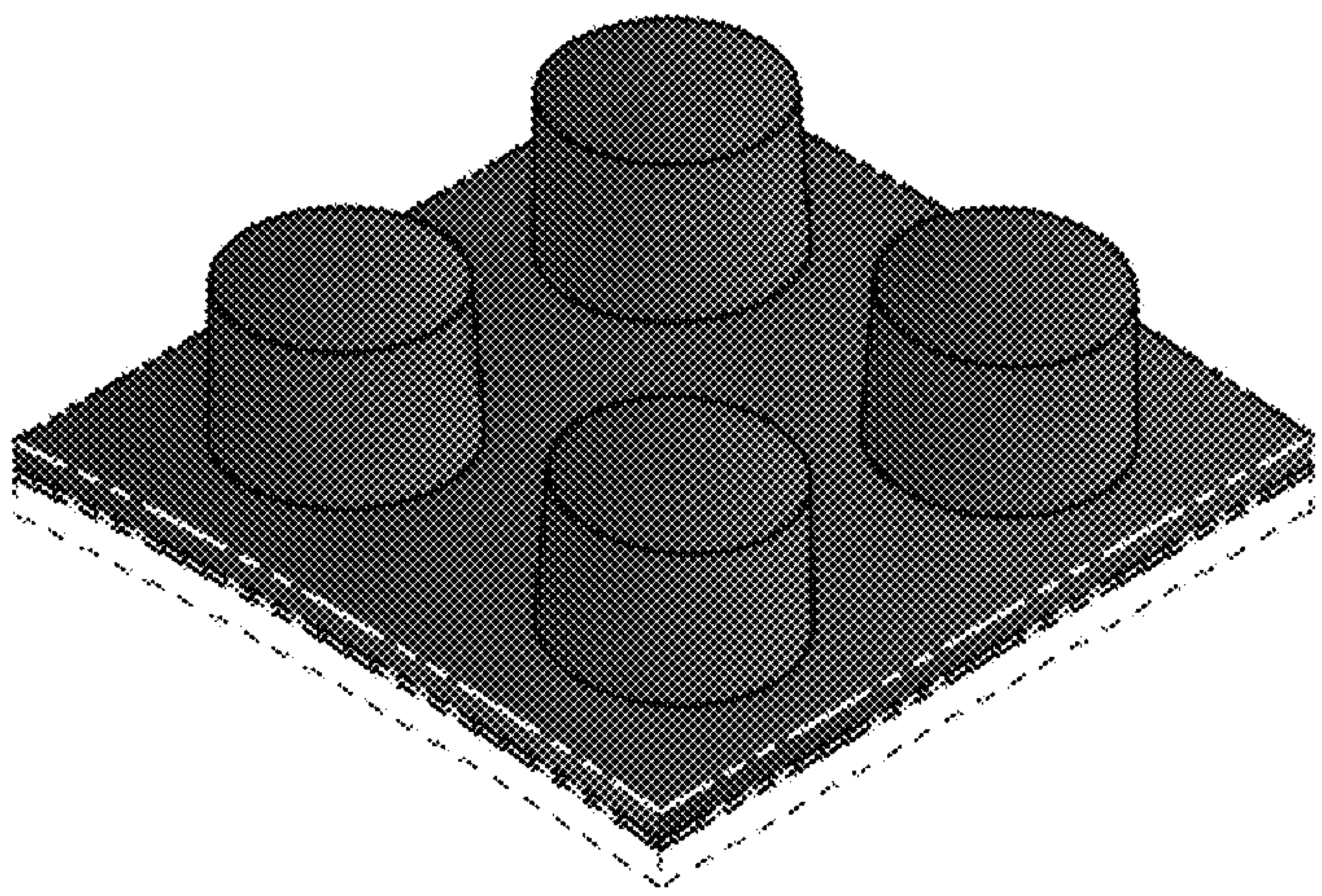

FIG. 21

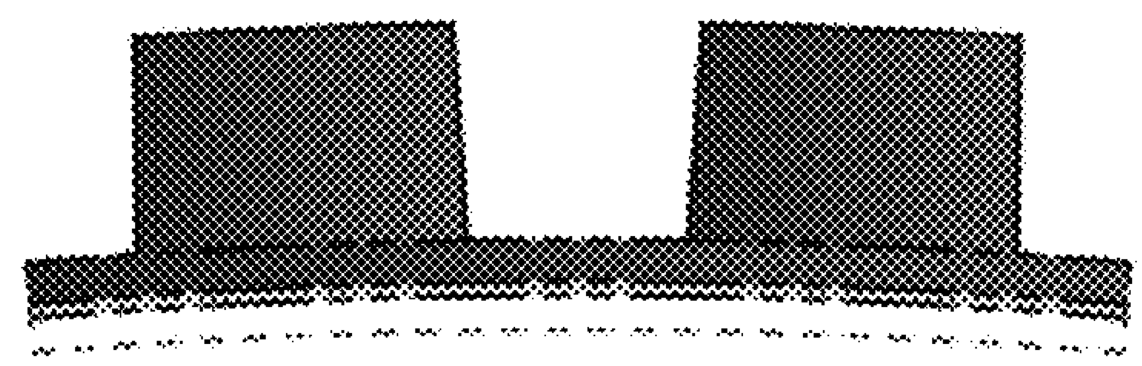

FIG. 22

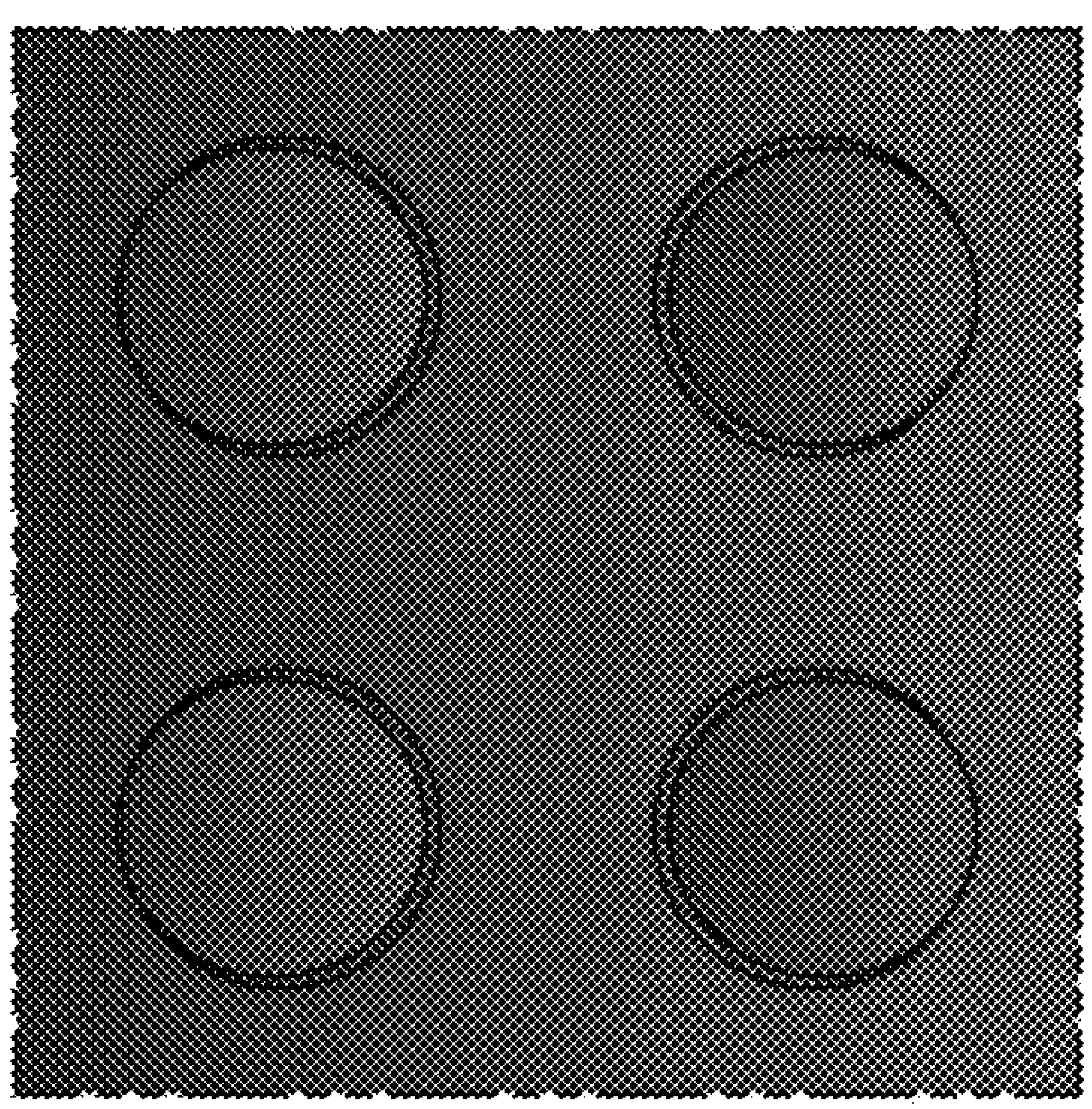

FIG. 23

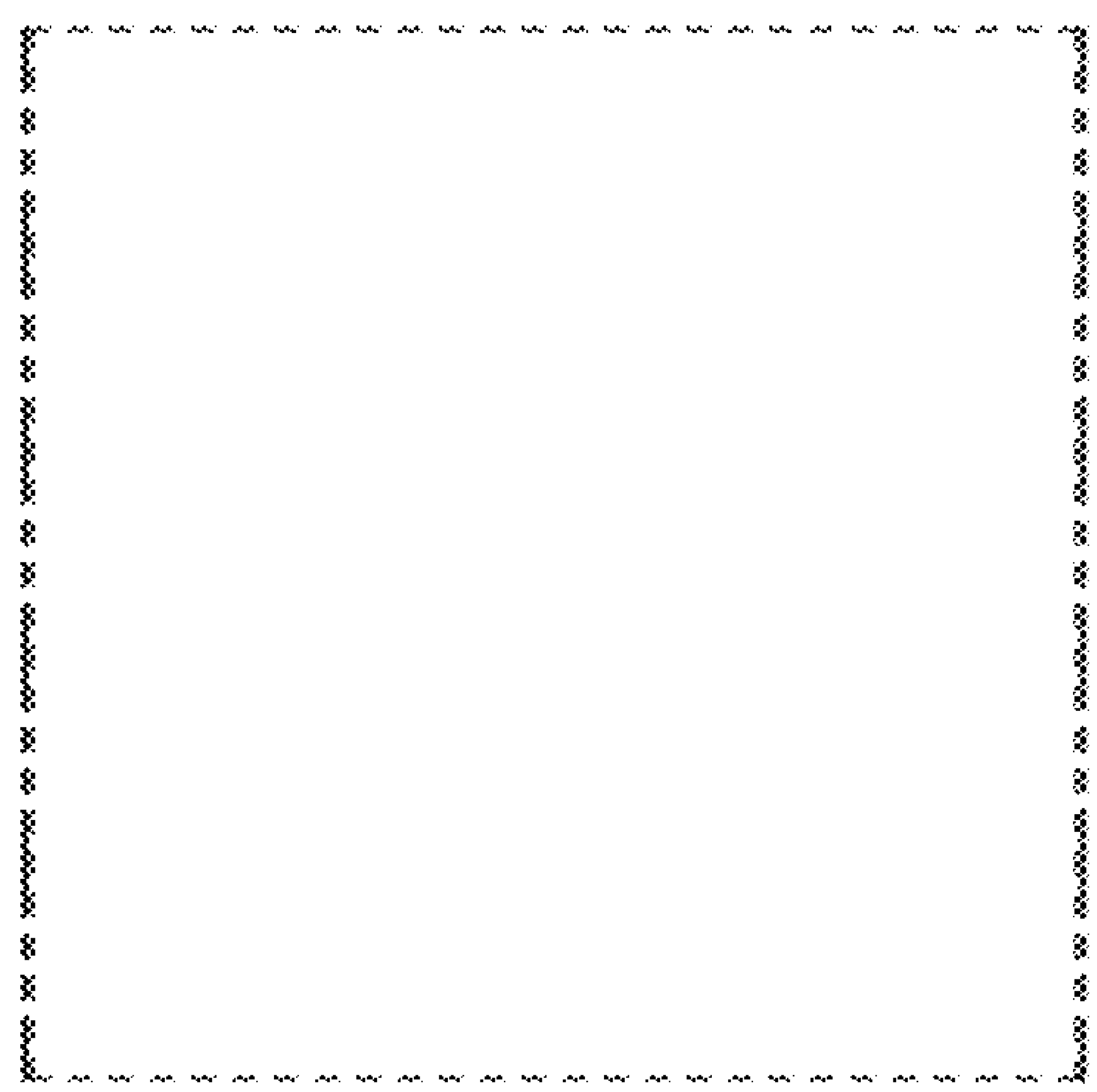

FIG. 24